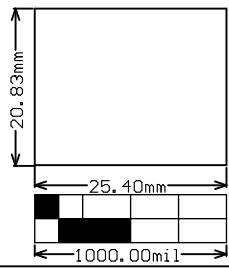


Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	1	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
○	6	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	10	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	
▽	6	37.40mil (0.950mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
□	5	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
	32 Total					



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